



- : 020122MR008 □□19ZU
- No. of pins.
  - Selective plating
    - 'S1,-05u" Min. gold in contact area/ 100u" Min. Tin in solder area.
    - 'S2,-Gold flash in contact area/ 100u" Min. Tin in solder area.
    - 'S3,-10u" Min. gold in contact area/ 100u" Min. Tin in solder area.
    - 'S4,-15u" Min. gold in contact area/ 100u" Min. Tin in solder area.
    - 'S5,-30u" Min. gold in contact area/ 100u" Min. Tin in solder area.
    - 'S6,-50u" Min. gold in contact area/ 100u" Min. Tin in solder area.

NO.	DESCRIPTION	MATERIAL	COLOR	REMARK
6	TOP SHELL	PHON.BRONZE	——	NICK PLATED
5	MIDDLE SHELL	PHON.BRONZE	——	NICK PLATED
4	SHELL	PHON.BRONZE	——	NICK PLATED
3	CAP	LCP	BLACK	UL 94V-0
2	TERMINAL	PHON.BRONZE	——	GOLD/TIN
1	HOUSING	LCP	BLACK	UL 94V-0

**SUYIN**  
CONNECTOR

CUSTOMER COPY TITLE: USB Series A Type Dual Port Dip Type

ECN (DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	APPRO.	SCALE	UNIT	mm	A4
EC1T-021101-04	B	02/11/01	B1: 增加塑膠孔 B2至 B7 鐵殼設計變更 B8: 增加新料號	冀軍	張志偉	Angle ±2° 30 ~ ±0.50 10 ~ 30 ±0.30 ~ 10 ±0.15	DRAW 鄭家奇 00/09/07 DESIGN 鄭家奇 00/09/07 CHECK 宋權哲 00/09/07 APPRO. 宋權哲 00/09/07	4:1	mm	A4	☉
	A	02/05/30	A1: 2.00±0.10→2.00±0.20 A2: 2.0→1.50 A3: 2.47→2.50 修改圖框圖號和品名								
	0		NEW								